

## EAST Search History

| Ref # | Hits | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|---|---|------------------|---------|------------------|
| L1    | 1    | "520923" and kamitake   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:01 |
| L2    | 2    | "5608267".pn.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:03 |
| L3    | 2    | "5753529".pn.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:04 |
| L4    | 2    | "4680618".pn.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:26 |
| L5    | 0    | (semiconductor chip die) with (hard with carbin) with (copper cu) with (tungsten w) with (mo)                             | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:30 |
| L6    | 0    | (semiconductor chip die) same (hard with carbin) same (copper cu) same (tungsten w) same (mo)                             | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:30 |
| L7    | 0    | (semiconductor chip die) same (hard with carbin) same (copper cu) same (tungsten w) same (mo)                             | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:31 |
| L8    | 0    | (semiconductor chip die ic flipchip (flip adj chip)) same (hard with carbin) same (copper cu) same (tungsten w) same (mo) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/04/02 08:31 |

## EAST Search History

|     |     |   |   |    |    |                  |
|-----|-----|---|---|----|----|------------------|
| L9  | 13  | (semiconductor chip die ic flipchip (flip adj chip)) same (hard with carbon) same (copper cu) same (tungsten w) same (mo) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/04/02 08:35 |
| L10 | 583 | (semiconductor chip die ic flipchip (flip adj chip)) and (hard with carbon) and (copper cu) and (tungsten w) and (mo)     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/04/02 08:35 |
| L11 | 570 | 10 not 9  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/04/02 08:36 |